

4 Mbit (512Kb x 8) Low Voltage OTP EPROM

- LOW VOLTAGE READ OPERATION: 2.7V to 3.6V
- FAST READ ACCESS TIME:
 - 70ns at $V_{CC} = 3.0 \text{V}$ to 3.6 V
 - 80ns at $V_{CC} = 2.7V$ to 3.6V
- PIN COMPATIBLE with M27C4001
- LOW POWER CONSUMPTION:
 - 15μA max Standby Current
 - 15mA max Active Current at 5MHz
- PROGRAMMING TIME 100µs/byte (typical)
- HIGH RELIABILITY CMOS TECHNOLOGY
 - 2,000V ESD Protection
 - 200mA Latchup Protection Immunity
- ELECTRONIC SIGNATURE
 - Manufacturer Code: 20h
 - Device Code: 41h



The M27W401 is a low voltage 4 Mbit EPROM offered in the OTP range (one time programmable). It is ideally suited for microprocessor systems requiring large data or program storage and is organised as 524,288 by 8 bits.

Table 1. Signal Names

A0-A18	Address Inputs
Q0-Q7	Data Outputs
Ē	Chip Enable
G	Output Enable
V _{PP}	Program Supply
V _{CC}	Supply Voltage
V _{SS}	Ground

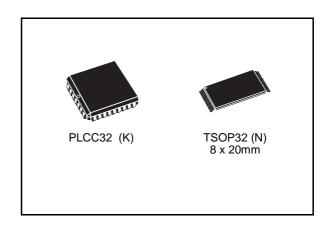
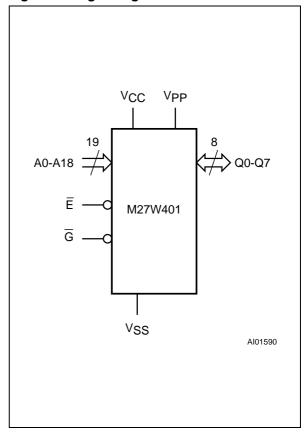


Figure 1. Logic Diagram



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Figure 2A. LCC Pin Connections

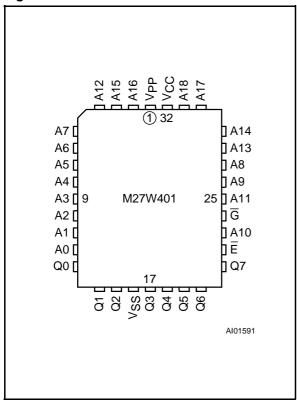


Figure 2B. TSOP Pin Connections

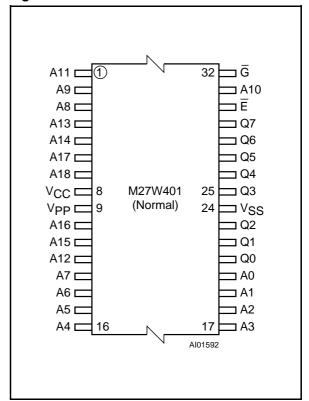


Table 2. Absolute Maximum Ratings (1)

Symbol	Parameter	Value	Unit
T _A	Ambient Operating Temperature (3)	-40 to 85	°C
T _{BIAS}	Temperature Under Bias	-50 to 125	°C
T _{STG}	Storage Temperature	-65 to 150	°C
V _{IO} (2)	Input or Output Voltages (except A9)	–2 to 7	V
V _{CC}	Supply Voltage	–2 to 7	V
V _{A9} ⁽²⁾	A9 Voltage	-2 to 13.5	V
V _{PP}	Program Supply Voltage	-2 to 14	V

Notes: 1. Except for the rating "Operating Temperature Range", stresses above those listed in the Table "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

3. Depends on range.

^{2.} Minimum DC voltage on Input or Output is -0.5V with possible undershoot to -2.0V for a period less than 20ns. Maximum DC Output is V_{CC} +0.5V with possible overshoot to V_{CC} +2V for a period less than 20ns.

Table 3. Operating Modes

Mode	Ē	G	A9	V _{PP}	Q0 - Q7
Read	V _{IL}	V _{IL}	X	V _{CC} or V _{SS}	Data Out
Output Disable	V _{IL}	V _{IH}	X	V _{CC} or V _{SS}	Hi-Z
Program	V _{IL} Pulse	V _{IH}	Х	V_{PP}	Data In
Verify	V _{IH}	V _{IL}	X	V_{PP}	Data Out
Program Inhibit	V _{IH}	V _{IH}	Х	V_{PP}	Hi-Z
Standby	V _{IH}	Х	Х	V _{CC} or V _{SS}	Hi-Z
Electronic Signature	V _{IL}	V _{IL}	V_{ID}	V _{CC}	Codes

Note: $X = V_{IH}$ or V_{IL} , $V_{ID} = 12V \pm 0.5V$

Table 4. Electronic Signature

Identifier	A0	Q7	Q6	Q5	Q4	Q3	Q2	Q1	Q0	Hex Data
Manufacturer's Code	V _{IL}	0	0	1	0	0	0	0	0	20h
Device Code	V _{IH}	0	1	0	0	0	0	0	1	41h

DESCRIPTION (cont'd)

The M27W401 operates in the read mode with a supply voltage as low as 2.7V at -40 to 85°C temperature range. The decrease in operating power allows either a reduction of the size of the battery or an increase in the time between battery recharges.

The M27W401 is offered in PLCC32 and TSOP32 (8 x 20mm) packages.

DEVICE OPERATION

The operating modes of the M27W401 are listed in the Operating Modes table. A single power supply is required in the read mode. All inputs are TTL levels except for V_{pp} and 12V on A9 for Electronic Signature.

Read Mode

The M27W401 has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable (\overline{E}) is the power control and should be used for device selection. Output Enable (\overline{G}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that the addresses are stable, the address access time (t_{AVQV}) is equal to the delay from \overline{E} to output (t_{ELQV}). Data is available at the output after a delay of t_{GLQV} from the falling edge of \overline{G} , assuming that \overline{E} has

been low and the addresses have been stable for at least tayou-tgLov.

Standby Mode

The M27W401 has a standby mode which reduces the supply current from 15mA to 15 μ A with low voltage operation V_{CC} \leq 3.6V, see Read Mode DC Characteristics table for details. The M27W401 is placed in the standby mode by applying a CMOS high signal to the \overline{E} input. When in the standby mode, the outputs are in a high impedance state, independent of the \overline{G} input.

Two Line Output Control

Because EPROMs are usually used in larger memory arrays, this product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

- a. the lowest possible memory power dissipation,
- b. complete assurance that output bus contention will not occur.

For the most efficient use of these two control lines, \overline{E} should be decoded and used as the primary device selecting function, while \overline{G} should be made a common connection to all devices in the array and connected to the \overline{READ} line from the system control bus. This ensures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is required from a particular memory device.

Table 5. AC Measurement Conditions

	High Speed	Standard
Input Rise and Fall Times	≤ 10ns	≤ 20ns
Input Pulse Voltages	0 to 3V	0.4V to 2.4V
Input and Output Timing Ref. Voltages	1.5V	0.8V and 2V

Figure 3. AC Testing Input Output Waveform

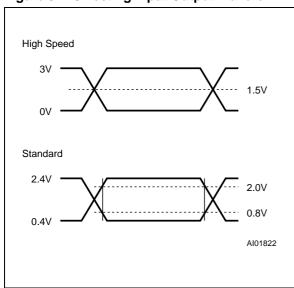


Figure 4. AC Testing Load Circuit

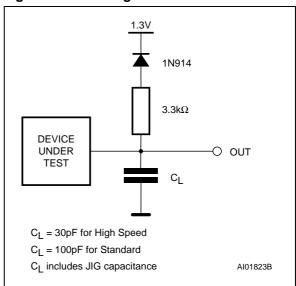


Table 6. Capacitance (1) $(T_A = 25 \, ^{\circ}C, f = 1 \, \text{MHz})$

Symbol	Parameter	Test Condition	Min	Max	Unit
C _{IN}	Input Capacitance	$V_{IN} = 0V$		6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V		12	pF

Note: 1. Sampled only, not 100% tested.

System Considerations

The power switching characteristics of Advanced CMOS EPROMs require careful decoupling of the devices. The supply current, I_{CC} , has three segments that are of interest to the system designer: the standby current level, the active current level, and transient current peaks that are produced by the falling and rising edges of \overline{E} . The magnitude of the transient current peaks is dependent on the capacitive and inductive loading of the device at the output.

The associated transient voltage peaks can be suppressed by complying with the two line output

control and by properly selected decoupling capacitors. It is recommended that a $0.1\mu F$ ceramic capacitor be used on every device between V_{CC} and $V_{SS}.$ This should be a high frequency capacitor of low inherent inductance and should be placed as close to the device as possible. In addition, a $4.7\mu F$ bulk electrolytic capacitor should be used between V_{CC} and V_{SS} for every eight devices. The bulk capacitor should be located near the power supply connection point.The purpose of the bulk capacitor is to overcome the voltage drop caused by the inductive effects of PCB traces.

Table 7. Read Mode DC Characteristics ⁽¹⁾ $(T_A = -40 \text{ to } 85 \text{ °C}; V_{CC} = 2.7 \text{V to } 3.6 \text{V}; V_{PP} = V_{CC})$

Symbol	Parameter	Test Condition	Min	Max	Unit
ILI	Input Leakage Current	$0V \le V_{IN} \le V_{CC}$		±10	μΑ
I _{LO}	Output Leakage Current	$0V \le V_{OUT} \le V_{CC}$		±10	μΑ
I _{CC}	Supply Current	$\overline{E} = V_{IL}, \overline{G} = V_{IL},$ $I_{OUT} = 0mA, f = 5MHz,$ $V_{CC} \le 3.6V$		15	mA
I _{CC1}	Supply Current (Standby) TTL	E = V _{IH}		1	mA
I _{CC2}	Supply Current (Standby) CMOS	\overline{E} > V_{CC} - 0.2V, $V_{CC} \le 3.6V$		15	μΑ
I _{PP}	Program Current	$V_{PP} = V_{CC}$		10	μΑ
V_{IL}	Input Low Voltage		-0.6	0.2 V _{CC}	V
V _{IH} ⁽²⁾	Input High Voltage		0.7 V _{CC}	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output High Voltage TTL	I _{OH} = -400μA	2.4		V

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}. 2. Maximum DC voltage on Output is V_{CC} +0.5V.

Table 8. Read Mode AC Characteristics ⁽¹⁾ $(T_A = -40 \text{ to } 85 \,^{\circ}\text{C}; \, V_{CC} = 2.7 \text{V to } 3.6 \text{V}; \, V_{PP} = V_{CC})$

				M27W401						
Symbol	Alt	Parameter	Test Condition		-80) ⁽³⁾		-10 (-120/-1		Unit
				$V_{CC} = 3.0$	V to 3.6V	V _{CC} = 2.7	V to 3.6V	V _{CC} = 2.7	V to 3.6V	
				Min	Max	Min	Max	Min	Max	
t _{AVQV}	t _{ACC}	Address Valid to Output Valid	$\overline{\underline{E}}_{=} V_{IL},$ $G = V_{IL}$		70		80		100	ns
t _{ELQV}	t _{CE}	Chip Enable Low to Output Valid	$\overline{G} = V_{IL}$		70		80		100	ns
t _{GLQV}	t _{OE}	Output Enable Low to Output Valid	$\overline{E} = V_{IL}$		40		50		60	ns
t _{EHQZ} (2)	t _{DF}	Chip Enable High to Output Hi-Z	$\overline{G} = V_{IL}$	0	50	0	50	0	60	ns
t _{GHQZ} (2)	t _{DF}	Output Enable High to Output Hi-Z	$\overline{E} = V_{IL}$	0	50	0	50	0	60	ns
t _{AXQX}	t _{OH}	Address Transition to Output Transition	$\overline{\underline{\underline{E}}} = V_{IL},$ $\overline{G} = V_{IL}$	0		0		0		ns

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.
2. Sampled only, not 100% tested.
3. Speed obtained with High Speed AC measurement conditions.

Figure 5. Read Mode AC Waveforms

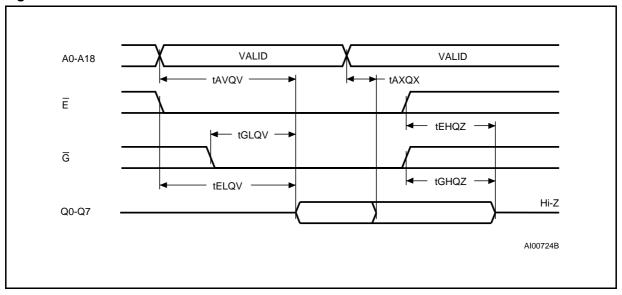


Table 9. Programming Mode DC Characteristics (1) (TA = 25 °C; VCC = 6.25V \pm 0.25V; VPP = 12.75V \pm 0.25V)

Symbol	Parameter	Test Condition	Min	Max	Unit
ILI	Input Leakage Current	$0 \le V_{IN} \le V_{CC}$		±10	μΑ
Icc	Supply Current			50	mA
I _{PP}	Program Current	E = V _{IL}		50	mA
V _{IL}	Input Low Voltage		-0.3	0.8	V
V _{IH}	Input High Voltage		2	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output High Voltage TTL	$I_{OH} = -400 \mu A$	2.4		V
V _{ID}	A9 Voltage		11.5	12.5	V

 $\textbf{Note:} \quad \text{1. } V_{CC} \text{ must be applied simultaneously with or before } V_{PP} \text{ and removed simultaneously or after } V_{PP}.$

Table 10 Programming Mode AC Characteristics $^{(1)}$ (TA = 25 °C; VCC = 6.25V \pm 0.25V; VPP = 12.75V \pm 0.25V)

Symbol	Alt	Parameter	Test Condition	Min	Max	Unit
t _{AVEL}	t _{AS}	Address Valid to Chip Enable Low		2		μs
t _{QVEL}	t _{DS}	Input Valid to Chip Enable Low		2		μs
t _{VPHEL}	t _{VPS}	V _{PP} High to Chip Enable Low		2		μs
t _{VCHEL}	t _{VCS}	V _{CC} High to Chip Enable Low		2		μs
t _{ELEH}	t _{PW}	Chip Enable Program Pulse Width		95	105	μs
t _{EHQX}	t _{DH}	Chip Enable High to Input Transition		2		μs
t _{QXGL}	t _{OES}	Input Transition to Output Enable Low		2		μs
t _{GLQV}	t _{OE}	Output Enable Low to Output Valid			100	ns
t _{GHQZ}	t _{DFP}	Output Enable High to Output Hi-Z		0	130	ns
t _{GHAX}	t _{AH}	Output Enable High to Address Transition		0		ns

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.

2. Sampled only, not 100% tested.

Figure 6. Programming and Verify Modes AC Waveforms

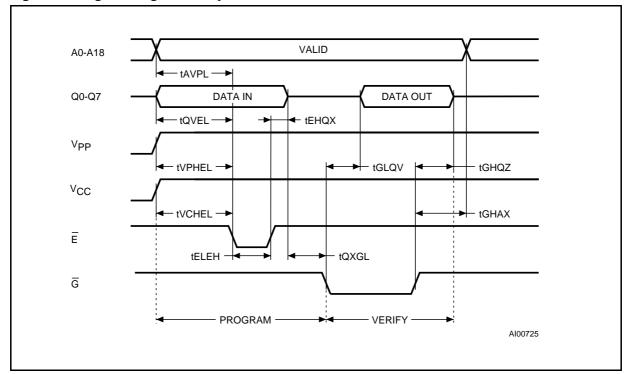
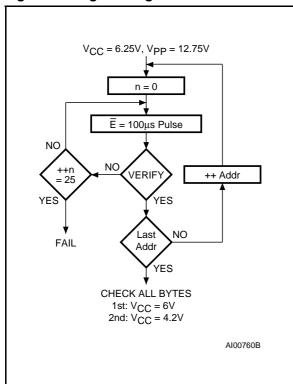


Figure 7. Programming Flowchart



Programming

The M27W401 has been designed to be fully compatible with the M27C4001 and has the same electronic signature. As a result the M27W401 can be programmed as the M27C4001 on the same programming equipment applying 12.75V on VPP and 6.25V on VCC by the use of the same PRESTO II algorithm.

When delivered, all bits of the M27W401 are in the '1' state. Data is introduced by selectively programming '0's into the desired bit locations. Although only '0's will be programmed, both '1's and '0's can be present in the data word. The M27W401 is in the programming mode when V_{PP} input is at 12.75V, \overline{G} is at V_{IH} and \overline{E} is pulsed to V_{IL} . The data to be programmed is applied to 8 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL. V_{CC} is specified to be 6.25V \pm 0.25V.

PRESTO II Programming Algorithm

PRESTO II Programming Algorithm allows the whole array to be programmed with a guaranteed margin, in a typical time of 52.5 seconds. Program-

ming with PRESTO II consists of applying a sequence of 100µs program pulses to each byte until a correct verify occurs (see Figure 7). During programming and verify operation, a MARGIN MODE circuit is automatically activated in order to guarantee that each cell is programmed with enough margin. No overprogram pulse is applied since the verify in MARGIN MODE at Vcc much higher than 3.6V, provides the necessary margin to each programmed cell.

Program Inhibit

Programming of multiple M27W401s in parallel with different data is also easily accomplished. Except for \overline{E} , all like inputs including \overline{G} of the parallel M27W401 may be common. A TTL low level pulse applied to a M27W401's \overline{E} input, with V_{PP} at 12.75V, will program that M27W401. A high level \overline{E} input inhibits the other M27W401s from being programmed.

Program Verify

A verify (read) should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with \overline{G} at V_{IL} , \overline{E} at V_{IH} , V_{PP} at 12.75V and V_{CC} at 6.25V.

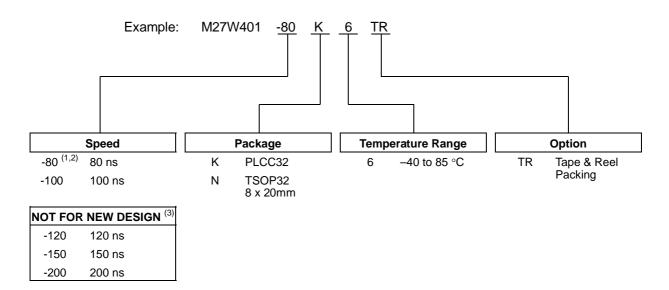
On-Board Programming

The M27W401 can be directly programmed in the application circuit. See the relevant Application Note AN620.

Electronic Signature

The Electronic Signature (ES) mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment to automatically match the device to be programmed with its corresponding programming algorithm. The ES mode is functional in the 25° C $\pm 5^{\circ}$ C ambient temperature range that is required when programming the M27W401. To activate the ES mode, the programming equipment must force 11.5V to 12.5V on address line A9 of the M27W401 with VPP=VCC=5V. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from VIL to VIH. All other address lines must be held at V_{IL} during Electronic Signature mode. Byte 0 (A0=V_{IL}) represents the manufacturer code and byte 1 (A0=V_{IH}) the device identifier code. For the STMicroelectronics M27W401, these two identifier bytes are given in Table 4 and can be read-out on outputs Q0 to Q7. Note that the M27W401 and M27C4001 have the same identifier bytes.

ORDERING INFORMATION SCHEME



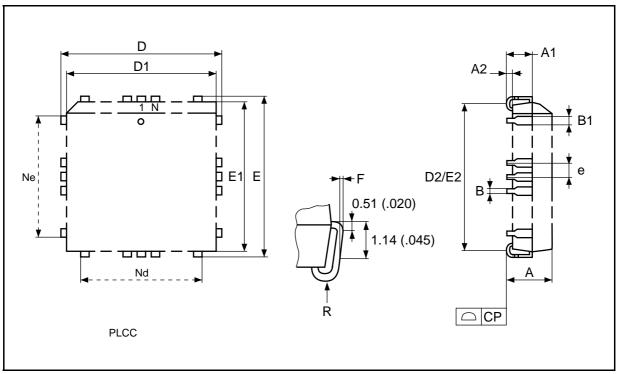
Notes: 1. High Speed, see AC Characteristics section for further information.

2. This speed also guarantees 70ns access time at $V_{\rm CC}$ = 3.0V to 3.6V. 3. These speeds are replaced by the 100ns.

For a list of available options (Speed, Package, etc...) or for further information on any aspect of this device, please contact the STMicroelectronics Sales Office nearest to you.

PLCC32 - 32 lead Plastic Leaded Chip Carrier, rectangular

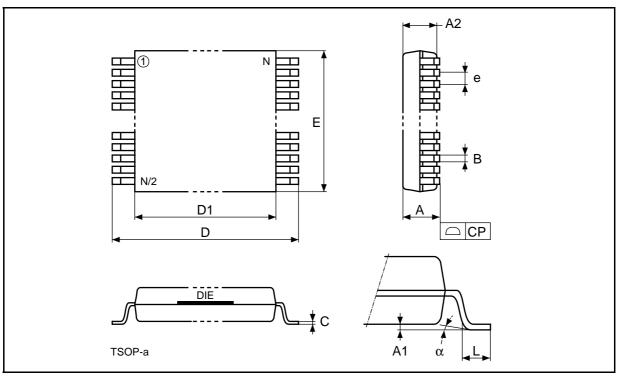
Symb		mm			inches	
Syllib	Тур	Min	Max	Тур	Min	Max
А		2.54	3.56		0.100	0.140
A1		1.52	2.41		0.060	0.095
A2		_	0.38		_	0.015
В		0.33	0.53		0.013	0.021
B1		0.66	0.81		0.026	0.032
D		12.32	12.57		0.485	0.495
D1		11.35	11.56		0.447	0.455
D2		9.91	10.92		0.390	0.430
E		14.86	15.11		0.585	0.595
E1		13.89	14.10		0.547	0.555
E2		12.45	13.46		0.490	0.530
е	1.27	_	_	0.050	_	_
F		0.00	0.25		0.000	0.010
R	0.89	_	_	0.035	_	_
N		32			32	
Nd		7			7	
Ne		9			9	
СР			0.10			0.004



Drawing is not to scale.

TSOP32 - 32 lead Plastic Thin Small Outline, 8 x 20mm

Symb		mm		inches			
Oyillo	Тур	Min	Max	Тур	Min	Max	
А			1.20			0.047	
A1		0.05	0.17		0.002	0.006	
A2		0.95	1.05		0.037	0.041	
В		0.15	0.27		0.006	0.011	
С		0.10	0.21		0.004	0.008	
D		19.80	20.20		0.780	0.795	
D1		18.30	18.50		0.720	0.728	
Е		7.90	8.10		0.311	0.319	
е	0.50	_	_	0.020	_	_	
L		0.50	0.70		0.020	0.028	
α		0°	5°		0°	5°	
N		32	<u> </u>		32	•	
СР			0.10			0.004	



Drawing is not to scale.

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